



Mobile Intel® CM246 Chipset

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Essentials

Product Collection	Intel® C240 Series Chipsets
Code Name	Products formerly Coffee Lake
Status	Launched
Launch Date	Q2'18
Bus Speed	8 GT/s DMI3
Lithography	14 nm
TDP	3 W
Recommended Customer Price	
Supports Overclocking	Yes

Supplemental Information

Embedded Options Available	Yes
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Memory Specifications

# of DIMMs per channel	2
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Processor Graphics

Intel® Clear Video Technology	Yes
# of Displays Supported †	3

Expansion Options

PCI Support	NO
PCI Express Revision	3.0
PCI Express Configurations †	x1, x2, x4
Max # of PCI Express Lanes	24

I/O Specifications

# of USB Ports	14
USB Configuration	10 Total USB 3.1 Ports - Up to 6 USB 3.1 Gen 2 Ports - Up to 10 USB 3.1 Gen 1 Ports 14 USB 2.0 Ports
USB Revision	3.1/2.0

Max # of SATA 6.0 Gb/s Ports

8

RAID Configuration [?](#)

0/1/5/10

Integrated LAN [?](#)

Integrated MAC

Integrated Wireless[‡]

Intel® Wireless-AC MAC

Package Specifications

Package Size

25mm x 24mm

Low Halogen Options Available

See MDDS

Advanced Technologies

Intel® Virtualization Technology for Directed I/O (VT-d) [‡] [?](#)

Yes

Intel® vPro™ Platform Eligibility [‡] [?](#)

Yes

Intel® ME Firmware Version [?](#)

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Intel® HD Audio Technology [?](#)

Yes

Intel® Rapid Storage Technology [?](#)

Yes

Intel® Rapid Storage Technology enterprise [?](#)

Yes

Intel® Stable Image Platform Program (SIPP) [?](#)

Yes

Intel® Smart Sound Technology [?](#)

Yes

Security & Reliability

Intel® Trusted Execution Technology [‡] [?](#)

Yes

More support options for Mobile Intel® CM246 Chipset



Product Support



Downloads and Software



Support Community



Warranty and Replacement



Need more help?

Contact support



Give Feedback

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

WARNING: Altering clock frequency and/or voltage may: (i) reduce system stability and useful life of the system and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance; (iv) cause additional heat or other damage; and (v) affect system data integrity. Intel has not tested, and does not warranty, the operation of the processor beyond its specifications. Intel assumes no responsibility that the processor, including if used with altered clock frequencies and/or voltages, will be fit for any particular purpose. For more information, visit <http://www.intel.com/content/www/us/en/gaming/overclocking/overclocking-intel-processors.html>



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